## Package Outline Drawing

## M20.173

20 LEAD THIN SHRINK SMALL OUTLINE PACKAGE (TSSOP) Rev 2, 5/10







– 1.00 REF-

GAUGE

PLANE

0°-8°

0.60 ±0.15

0.25







## NOTES:

0.90 +0.15/-0.10

0.05 MIN 0.15 MAX

<u>A</u> Dimension does not include mold flash, protrusions or gate burrs. Mold flash, protrusions or gate burrs shall not exceed 0.15 per side.

DETAIL "X"

- 2. Dimension does not include interlead flash or protrusion. Interlead flash or protrusion shall not exceed 0.25 per side.
- 3. Dimensions are measured at datum plane H.
- 4. Dimensioning and tolerancing per ASME Y14.5M-1994.
- 5. Dimension does not include dambar protrusion. Allowable protrusion shall be 0.08mm total in excess of dimension at maximum material condition. Minimum space between protrusion and adjacent lead is 0.07mm.
- 6. Dimension in ( ) are for reference only.
- 7. Conforms to JEDEC MO-153.

